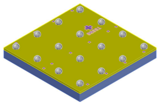
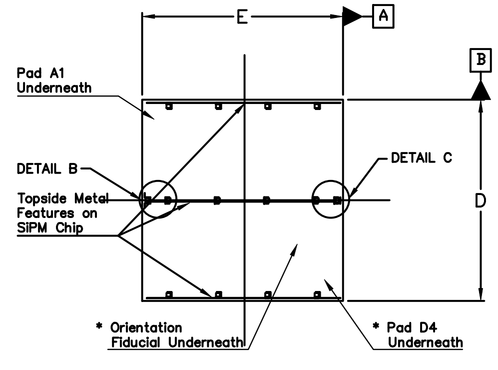
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

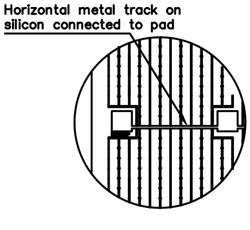


ODCSP16 4x4, 1.12P
CASE 570CN
ISSUE A

DATE 07 JAN 2021

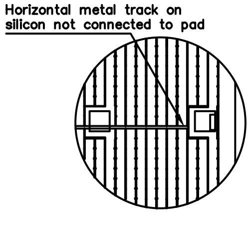


TOP VIEW



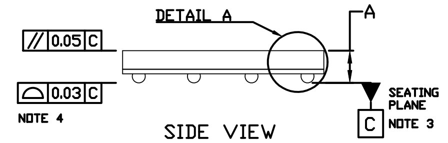
DETAIL B

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. SOLDER BALLS ARE PERFECTLY ALIGNED TO THE CENTER OF THE SENSOR (ACTIVE AREA).

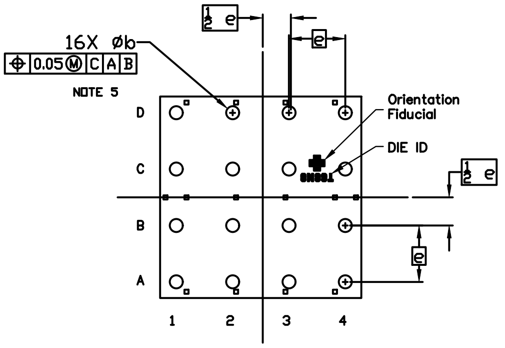


DETAIL C

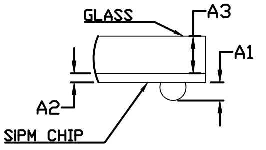
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.60	0.64	0.68
A1	0.16	0.18	0.20
A2	0.075	0.09	0.105
A3	0.355	0.37	0.385
b	0.23	0.26	0.29
D	3.95	4.00	4.05
E	3.95	4.00	4.05
e	1.12 BSC		



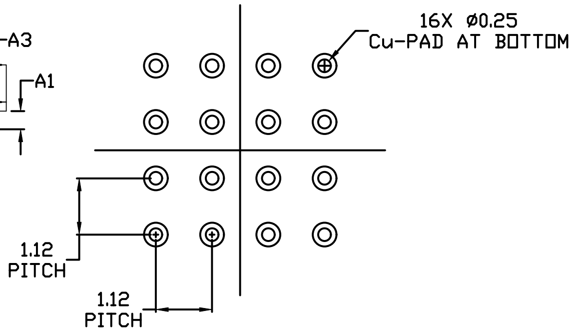
SIDE VIEW



BOTTOM VIEW



DETAIL A



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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